SDFS019B - JANUARY 1989 - REVISED JANUARY 1997

 Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

#### description

These devices contain four independent 2-input exclusive-OR gates. They perform the Boolean function  $Y = A \oplus B$  or  $Y = \overline{AB} + A\overline{B}$  in positive logic.

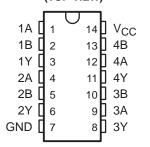
A common application is as a true/complement element. If one of the inputs is low, the other input is reproduced in true form at the output. If one of the inputs is high, the signal on the other input is reproduced inverted at the output.

The SN54F86 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74F86 is characterized for operation from 0°C to 70°C.

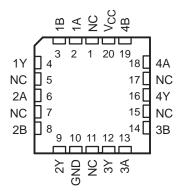
# FUNCTION TABLE (each gate)

INP	UTS	OUTPUT
Α	В	Y
L	L	L
L	Н	н
Н	L	н
Н	Н	L

#### SN54F86...J PACKAGE SN74F86...D OR N PACKAGE (TOP VIEW)

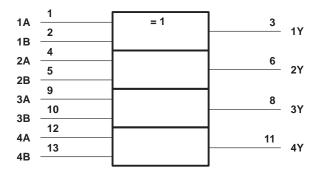


# SN54F86 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

## logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, and N packages.



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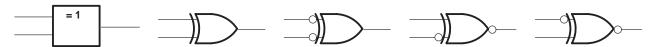


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#### exclusive-OR logic

An exclusive-OR gate has many applications, some of which can be represented better by alternative logic symbols.

#### **EXCLUSIVE OR**



These are five equivalent exclusive-OR symbols valid for an 'F86 gate in positive logic; negation may be shown at any two ports.

# The output is active (low) if all inputs stand at the same logic level (i.e., A = B). EVEN-PARITY ELEMENT ODD-PARITY ELEMENT The output is active (low) if an even number of inputs (i.e., one 2) are active. The output is active (high) if an odd number of outputs (i.e., only 1 of the 2) are active.

absolute maximum rating	as over operatin	a free-air temp	erature range (	(unless otherwise noted)†
	,	g • • • • • • • • • • • • • • • • •	, , , , , , , , , , , , , , , , , , , ,	( )

Supply voltage range, V <sub>CC</sub>	-0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	
Input current range	-30 mA to 5 mA
Voltage range applied to any output in the high state	. $-0.5 \text{ V to V}_{CC}$
Current into any output in the low state	40 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2): D package	127°C/W
N package	
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### recommended operating conditions

		SN54F86			5	UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
V <sub>I</sub> L	Low-level input voltage			0.8			0.8	V
I <sub>IK</sub>	Input clamp current			-18			-18	mA
loh	High-level output current			-1			-1	mA
l <sub>OL</sub>	Low-level output current			20			20	mA
TA	Operating free-air temperature	-55		125	0		70	°C



NOTES: 1. The input voltage ratings may be exceeded provided the input current ratings are observed.

<sup>2.</sup> The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEST CONDITIONS				9			
PARAMETER	TES				MAX	MIN	5N74F86 TYP <sup>†</sup>	MAX	UNIT
VIK	V <sub>CC</sub> = 4.5 V,	I <sub>I</sub> = -18 mA			-1.2			-1.2	V
V	V <sub>CC</sub> = 4.5 V,	I <sub>OH</sub> = −1 mA	2.5	3.4		2.5	3.4		V
VOH	$V_{CC} = 4.75 V$ ,	$I_{OH} = -1 \text{ mA}$				2.7			V
V <sub>OL</sub>	$V_{CC} = 4.5 \text{ V},$	$I_{OL} = 20 \text{ mA}$		0.3	0.5		0.3	0.5	V
Ι <sub>Ι</sub>	$V_{CC} = 5.5 V$ ,	V <sub>I</sub> = 7 V			0.1			0.1	mA
lіН	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 2.7 V			20			20	μΑ
Ι <sub>ΙL</sub>	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 0.5 V			- 0.6			- 0.6	mA
los <sup>‡</sup>	V <sub>CC</sub> = 5.5 V,	VO = 0	-60		-150	-60		-150	mA
Іссн	V <sub>CC</sub> = 5.5 V,	See Note 3		15	23		15	23	mA
<sup>I</sup> CCL	$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 4.5 V		18	28		18	28	mA

<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

#### switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	C <sub>I</sub> R <sub>I</sub>	CC = 5 V L = 50 pl L = 500 s A = 25°C	<b>F,</b> Ω <b>,</b>	$V_{CC}$ = 4.5 V to 5.5 V, $C_L$ = 50 pF, $R_L$ = 500 $\Omega$ , $T_A$ = MIN to MAX§				UNIT
			′F86			SN54F86		SN74F86		
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A or B	Y	3	4	5.5	3	7	3	6.5	
t <sub>PHL</sub>	(other input low)		3	4.2	5.5	2.6	8	3	6.5	ns
t <sub>PLH</sub>	A or B	V	3.5	5.3	7	3.5	10	3.5	8	ns
t <sub>PHL</sub>	(other input high)	·	3	4.7	6.5	3	8	3	7.5	115

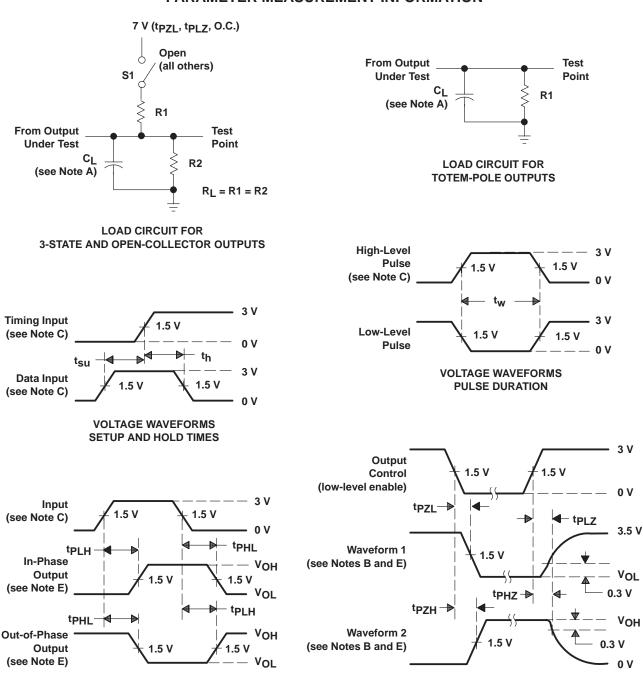
<sup>§</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



<sup>‡</sup> Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTE 3: I<sub>CCH</sub> is measured with outputs open, and the A or B input (not both) at 4.5 V. Remaining inputs are grounded.

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

**VOLTAGE WAVEFORMS** 

PROPAGATION DELAY TIMES (see Note D)

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics:  $PRR \le 1 \text{ MHz}$ ,  $t_r = t_f \le 2.5 \text{ ns}$ , duty cycle = 50%.

**VOLTAGE WAVEFORMS** 

**ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS** 

- D. When measuring propagation delay times of 3-state outputs, switch S1 is open.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms



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#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74F86DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	F86	Samples
SN74F86DRG4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	F86	Samples
SN74F86N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74F86N	Samples
SN74F86NE4	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74F86N	Samples
SN74F86NSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74F86	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.



### PACKAGE OPTION ADDENDUM

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## **PACKAGE MATERIALS INFORMATION**

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#### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74F86DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74F86NSR	so	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

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#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74F86DR	SOIC	D	14	2500	356.0	356.0	35.0
SN74F86NSR	SO	NS	14	2000	356.0	356.0	35.0

# **PACKAGE MATERIALS INFORMATION**

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#### **TUBE**



\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74F86N	N	PDIP	14	25	506	13.97	11230	4.32
SN74F86N	N	PDIP	14	25	506	13.97	11230	4.32
SN74F86NE4	N	PDIP	14	25	506	13.97	11230	4.32
SN74F86NE4	N	PDIP	14	25	506	13.97	11230	4.32

#### **MECHANICAL DATA**

## NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



# D (R-PDSO-G14)

#### PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



# D (R-PDSO-G14)

# PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



# N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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